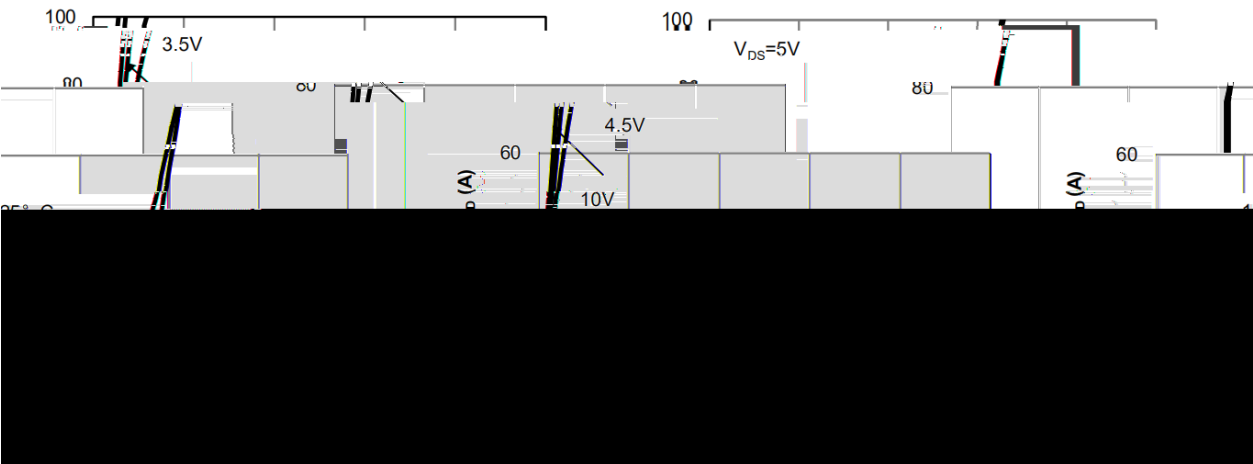
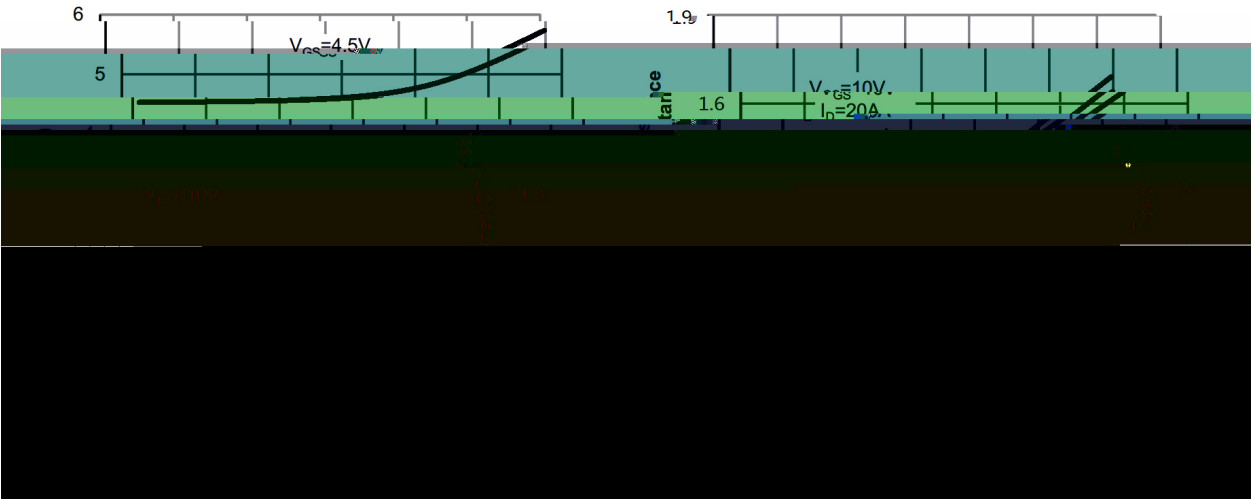
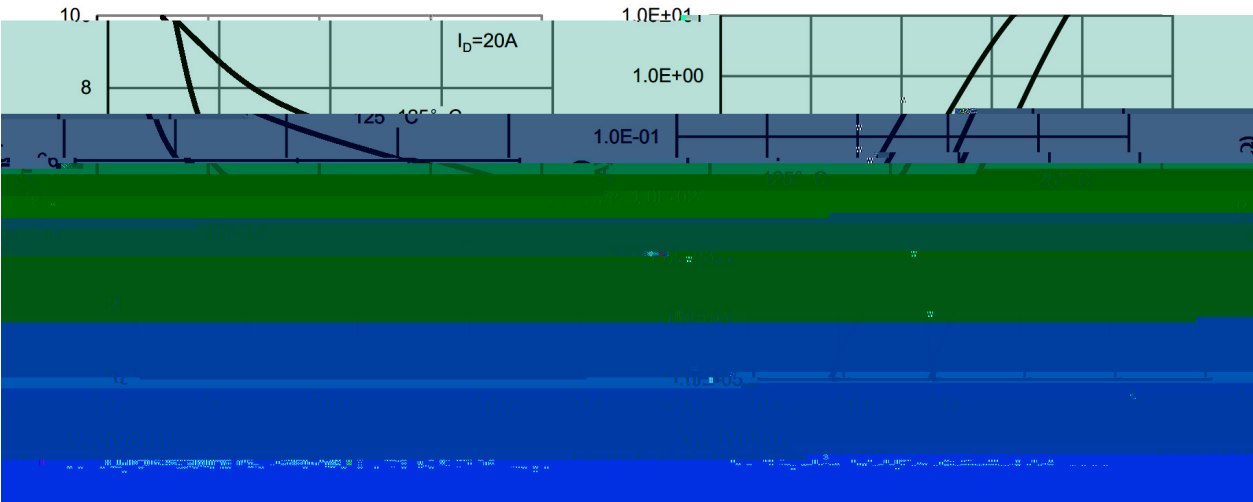


/ Absolute Maximum Ratings(Ta=25 °C)

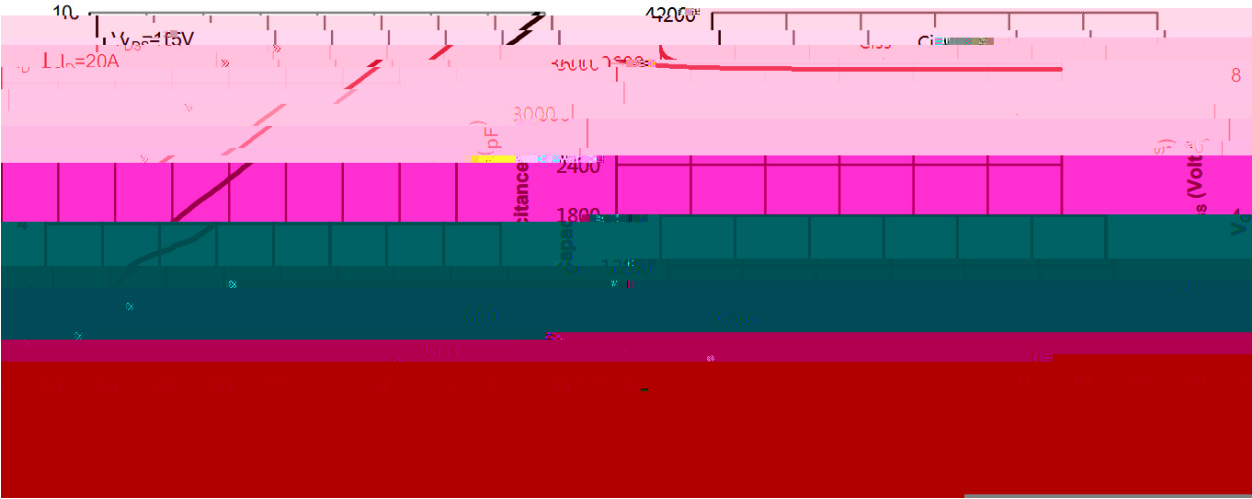
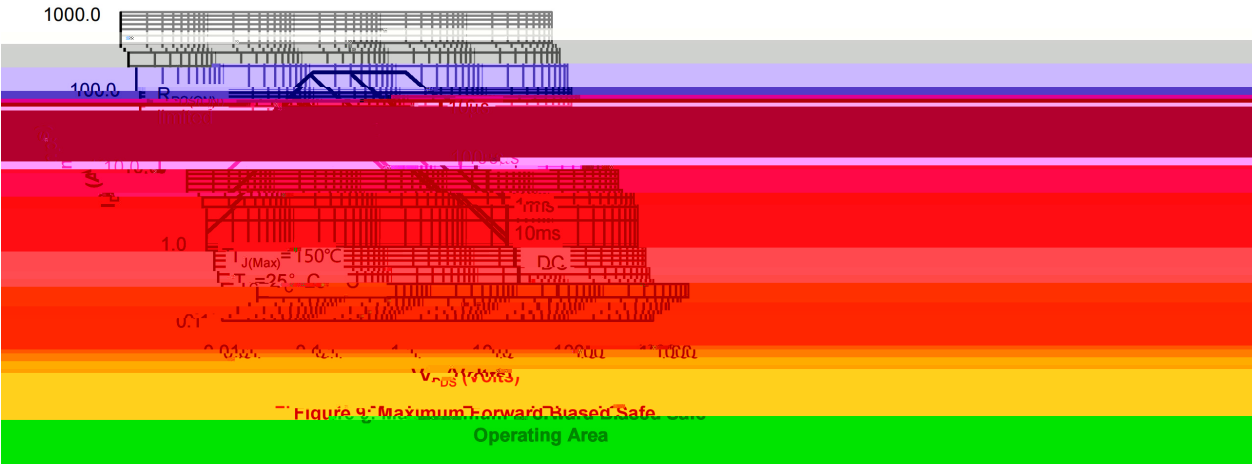
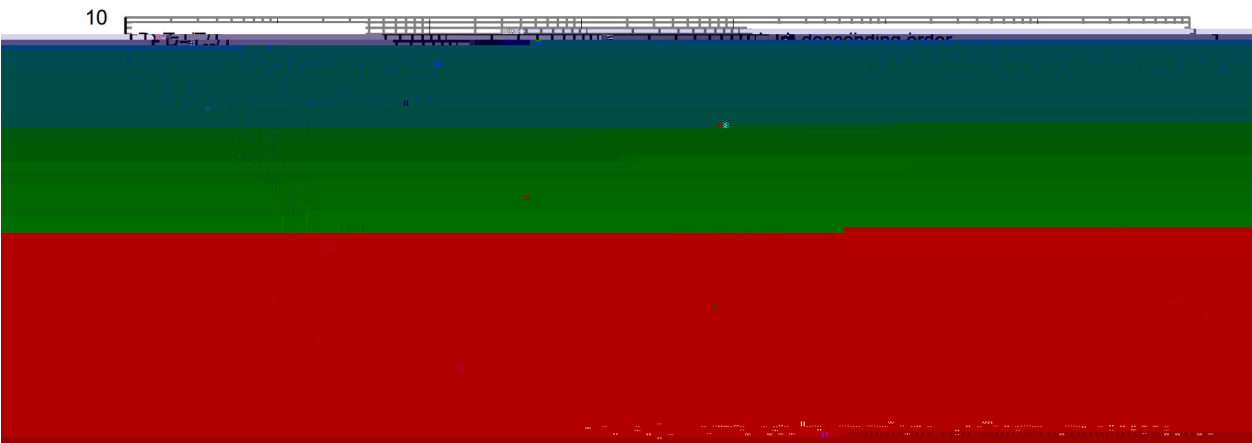
Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DS}	30	V
Drain Current		$I_D(T_c=25^\circ\text{C})$	76	A
Drain Current - Pulsed		I_{DM}	190	A
Gate-Source Voltage		V_{GS}	± 20	V
Single Pulsed Avalanche Energy		E_{AS}	449	mJ
Avalanche Current		I_{AS}	33.5	A
Power Dissipation		$P_D(T_c=25^\circ\text{C})$	35	W
Operating and Storage Temperature Range		T_J, T_{stg}	-55 to 150	
Junction-to-Ambient	$t \leq 10$	$R_{\theta JA}$	42	/W
Junction-to-Ambient	Steady-State		78	
Junction-to-Case	Steady-State	$R_{\theta JC}$	3.6	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	30	35		V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =30V V _{GS} =0V			1	μA
Gate-Body Leakage Current Forward	I _{GSS}	V _{GS} =±20V V _{DS} =0V			±0.1	μA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} I _D =250μA	1.0	1.5	3.0	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V I _D =20A		3.3	3.5	mΩ
		V _{GS} =4.5V I _D =10A		4.7	6.5	mΩ
Drain-Source Diode Forward Voltage	V _{SD}	V _{GS} =0V I _S =1A			1.2	V
Input Capacitance	C _{iss}	V _{DS} =25V V _{GS} =0V f=1.0MHz		3470		pF
Output Capacitance	C _{oss}			270		
Reverse Transfer Capacitance	C _{rss}			240		
Gate resistance	R _g	V _{GS}				

/ Electrical Characteristic Curve



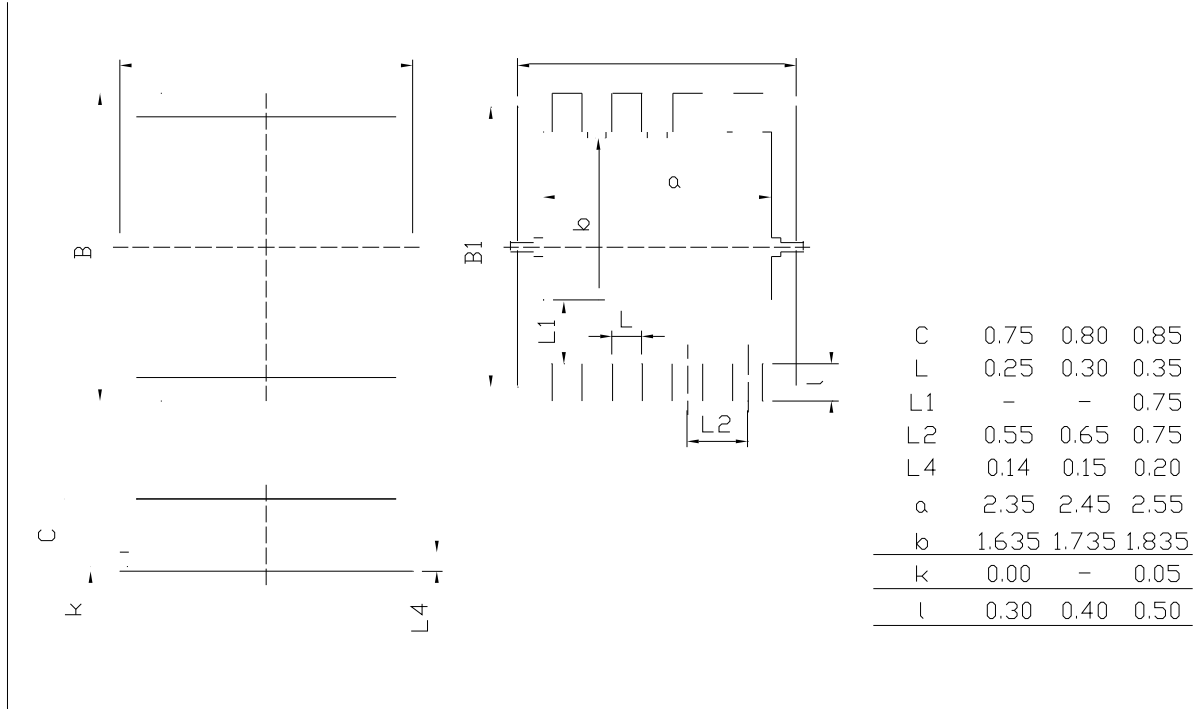
/ Electrical Characteristic Curve



/ Package Dimensions

PDFN3X3A-8L

Unit:mm



/ Marking Instructions



公司代码	BR	公司代码
产品型号	035N03	产品型号
批次号	----	批次号 1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27 28 29 30 31 32 33 34 35 36 37 38 39 40 41 42 43 44 45 46 47 48 49 50 51 52 53 54 55 56 57 58 59 60 61 62 63 64 65 66 67 68 69 70 71 72 73 74 75 76 77 78 79 80 81 82 83 84 85 86 87 88 89 90 91 92 93 94 95 96 97 98 99 100
Note:		
BR:	Company Code	
035N03:	Product Type Code	
****:	Lot No. Code, code change with Lot No	

() / Temperature Profile for IR Reflow Soldering(Pb-Free)

备注：

- 1 预热 150℃~180℃，时间 60~90sec;
- 2 峰值温度 245±5℃，时间 5~0.5sec;
- 3 冷却速度 2~10℃/sec.

Note:

- 1.Preheating:150~180℃，Time:60~90sec.
- 2.Peak Temp.:245±5℃，Duration:5~0.5sec.
3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

温度 260±5℃ 时间 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

包装形式 / REEL